

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S61	1	measur\$4 with resistance with wafer same manufatur\$4 same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:14
S62	11	measur\$4 with resistance with wafer same test\$4 same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:15
S63	0	measur\$4 with resistance with wafer same test\$4 and distribution with resistance and offset	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:15
S64	11	measur\$4 with resistance with wafer and distribution with resistance and offset	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:18
S65	3	measur\$4 with resistance with wafer and distribution with resistance and offset and resistance with (design model)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:18
S66	5	measur\$4 with resistance with wafer and distribution with resistance and correlat\$3 and resistance with (design model)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:24
S67	15	manufatur\$3 with (wafer semiconductor) and measur\$4 with resistance with wafer and correlat\$4 same (design model)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:26
S68	2	manufatur\$3 with (wafer semiconductor) and measur\$4 with resistance with wafer and correlat\$4 same (design model) and distribution same resistance	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/17 14:27
S69	18	manufatur\$3 with (wafer semiconductor) and measur\$4 with resistance with wafer and distribution same resistance and adjust\$4 with resistance and (model design\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:42
S70	10	702/84.ccls. and measur\$4 with resistance and manufatur\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:42
S71	8	702/84.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:43

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S72	1	702/84.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resistance	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:43
S73	1	702/84.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:43
S74	0	702/81.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:43
S75	0	702/81.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:43
S76	0	702/82.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:44
S77	0	702/83.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:44
S78	9	324/763.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:44
S79	21	324/765.ccls. and measur\$4 with resistance and manufatur\$4 and adjust\$3 with resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/10/18 13:45

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(manufactur\$3 with (wafer semiconductor) and measur\$4 with resistance with wafer and distribution same resistance and adjust\$4 with resistance and (model design\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/03/19 15:48
L2	2	(measur\$4 with resistance and resistance with design and adjust\$4 with resistance and manufactur\$4 with wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/03/19 15:48
L3	0	(resistance with distribution and offset and (chang\$4 increas\$4 decreas\$4) near resist\$4 and manufactur\$4 and wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/03/19 15:48
L4	0	(measur\$4 with resistance with potentiometer and compar\$4 with resistance and (adjust\$4 vary varying variable chang\$4) with resistance and manufactur\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/03/19 15:49